

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	79	Ohuchi near2 Shinji.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/21 03:23
L3	756	Yamada near2 Shigeru.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/21 03:24
L4	170	Shiraishi near2 Yasushi.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/21 03:24
L7	1904	257/686.ccls. and (chip die) and (bump ball terminal) and (encapsulant encapsulat\$3 mold \$3 seal\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/21 03:27
L8	484	257/685.ccls. and (chip die) and (bump ball terminal) and (encapsulant encapsulat\$3 mold \$3 seal\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/21 03:27
L9	1508	257/777.ccls. and (chip die) and (bump ball terminal) and (encapsulant encapsulat\$3 mold \$3 seal\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/21 03:27
L10	2157	257/778.ccls. and (chip die) and (bump ball terminal) and (encapsulant encapsulat\$3 mold \$3 seal\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/21 03:27

L11	1246	257/784.ccls. and (chip die) and (bump ball terminal) and (encapsulant encapsulat\$3 mold \$3 seal\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/21 03:28
L12	1413	257/723.ccls. and (chip die) and (bump ball terminal) and (encapsulant encapsulat\$3 mold \$3 seal\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/21 03:28
L13	585	257/773.ccls. and (chip die) and (bump ball terminal) and (encapsulant encapsulat\$3 mold \$3 seal\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/21 03:28
L14	1699	257/787.ccls. and (chip die) and (bump ball terminal) and (encapsulant encapsulat\$3 mold \$3 seal\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/21 03:28
L15	343	257/673.ccls. and (chip die) and (bump ball terminal) and (encapsulant encapsulat\$3 mold \$3 seal\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/21 03:28
L16	206	257/790.ccls. and (chip die) and (bump ball terminal) and (encapsulant encapsulat\$3 mold \$3 seal\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/21 03:28
L17	848	257/786.ccls. and (chip die) and (bump ball terminal) and (encapsulant encapsulat\$3 mold \$3 seal\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/21 03:28

L18	90	257/E25.006	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/01/21 03:29
L19	157	257/E25.013	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/01/21 03:30
L20	36	257/E25.018	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/01/21 03:30
L21	43	257/E25.021	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/01/21 03:31
L22	59	257/E25.027	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/01/21 03:31
L23	57	257/E21.614	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/01/21 03:31
L24	174	257/E23.085	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/01/21 03:31
L25	55	257/E31.117	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/01/21 03:31
L26	11	257/E31.118	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/01/21 03:31

L27	113	257/E51.02	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/01/21 03:32
L28	114	257/E23.116	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/01/21 03:32
L29	2	("6774473").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/01/21 03:36
L30	699	257/783.ccls. and (chip die) and (bump ball terminal) and (encapsulant encapsulat\$3 mold \$3 seal\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/21 03:39
L31	491	257/782.ccls. and (chip die) and (bump ball terminal) and (encapsulant encapsulat\$3 mold \$3 seal\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/21 03:41

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